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United States Design Patent

Lai et al.

(10)

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(54) HEAT DISSIPATION MODULE

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(**) Term: 15 Years

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(57) CLAIM

The ornamental design for a heat dissipation module as shown and described.

DESCRIPTION

FIG. 1 is a front perspective view of a heat dissipation module showing our new design;

FIG. 2 is a rear perspective view thereof;

FIG. 3 is a front view thereof;

FIG. 4 is a rear view thereof;

FIG. 5 is a left side view thereof;

FIG. 6 is a right side view thereof;

FIG. 7 is a top view thereof;

FIG. 8 is a bottom view thereof; and,

FIG. 9 is an enlarged view of the portion, labeled '9' of FIG. 1.

The evenly-dashed broken lines illustrate portions of the heat dissipation module that form no part of the claimed design. The dot-dashed broken lines depict the limits of the enlarged views and form no part for the claimed design.

1 Claim, 7 Drawing Sheets

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(30) Foreign Application Priority Data

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(51) LOC (15) Cl. 13-03

(52) U.S. Cl.

USPC D13/179; D23/370

(58) Field of Classification Search

USPC D13/112, 122, 177, 179, 184, 199;
D23/328, 370, 371, 377, 411, 412, 413;
454/15, 101, 102, 140, 208

CPC F04D 19/002; F04D 25/166; F04D 29/28;
F04D 29/281; F04D 29/325; F04D
29/422; H05K 7/2019; H05K 7/20172;
H05K 7/20136; H05K 7/20209

See application file for complete search history.

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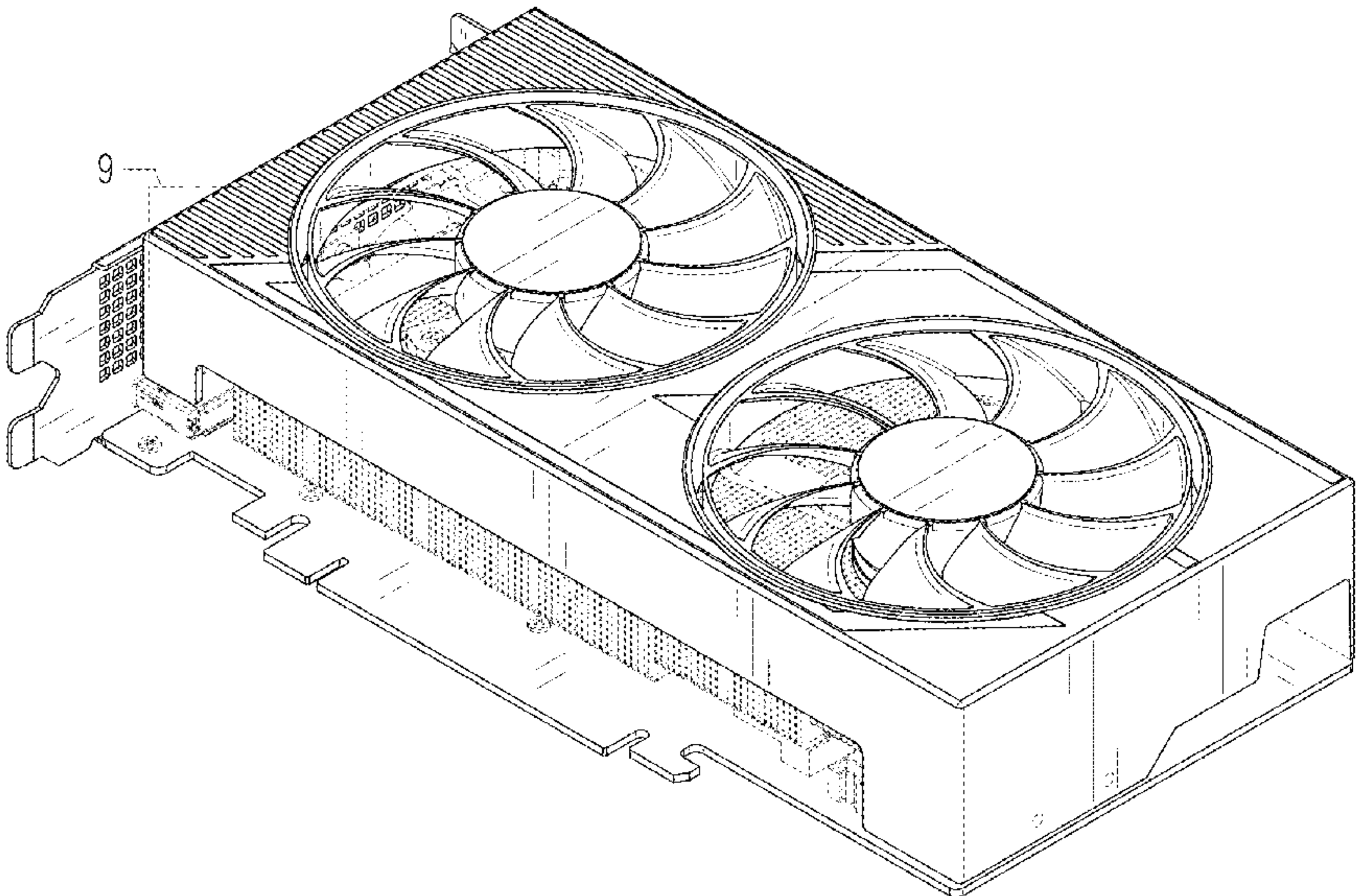
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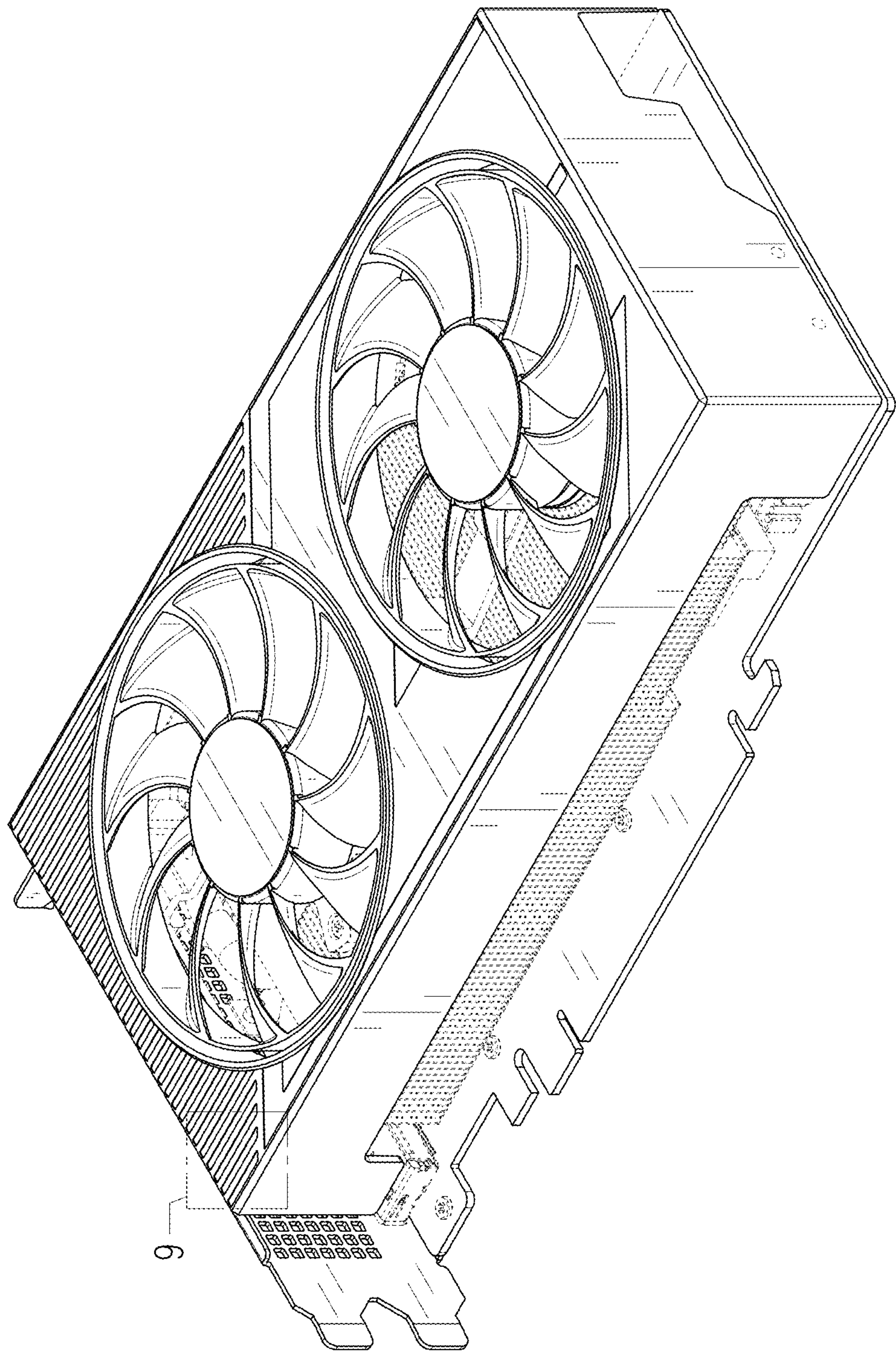


FIG. 1

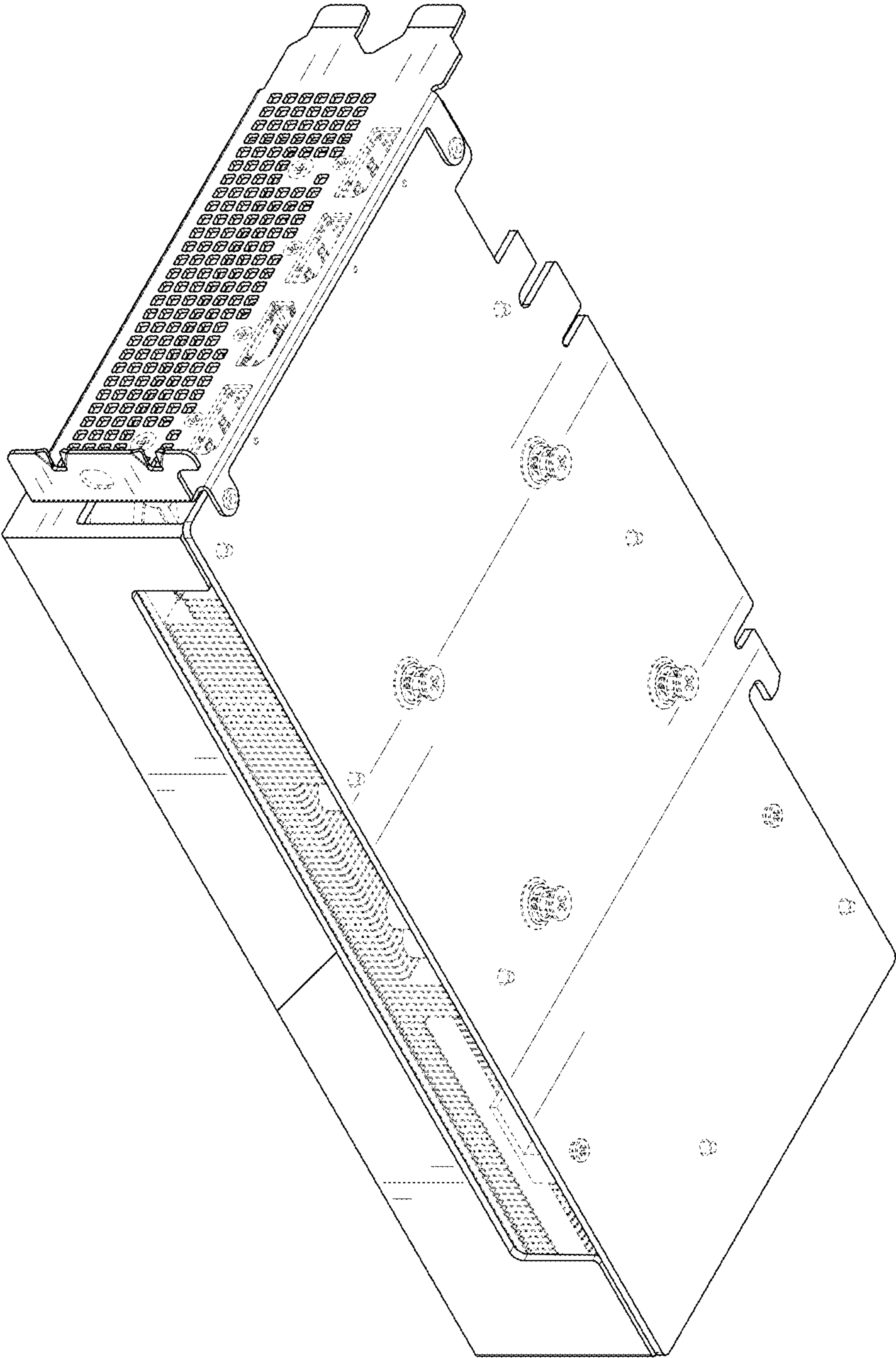


FIG. 2

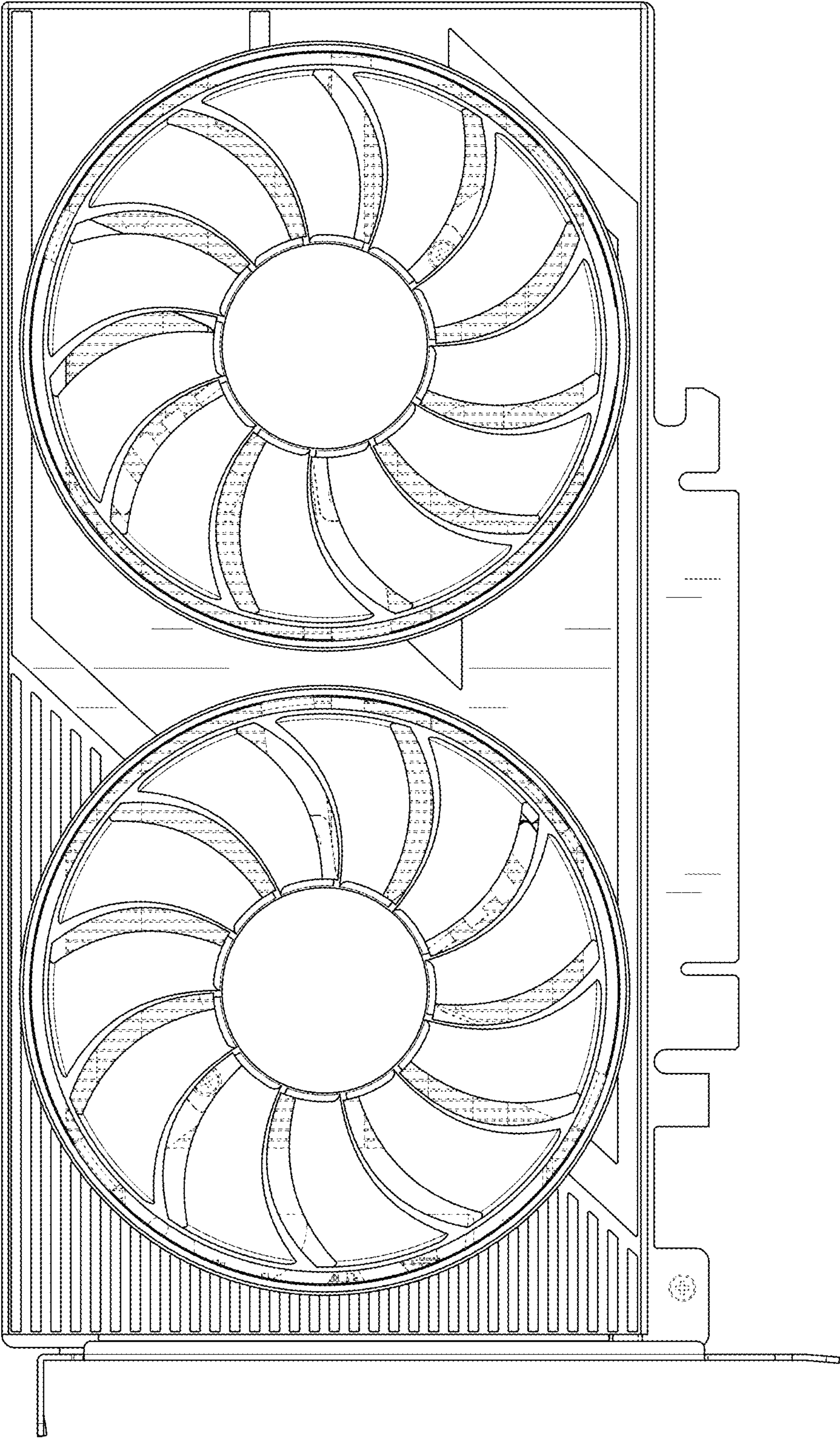


FIG. 3

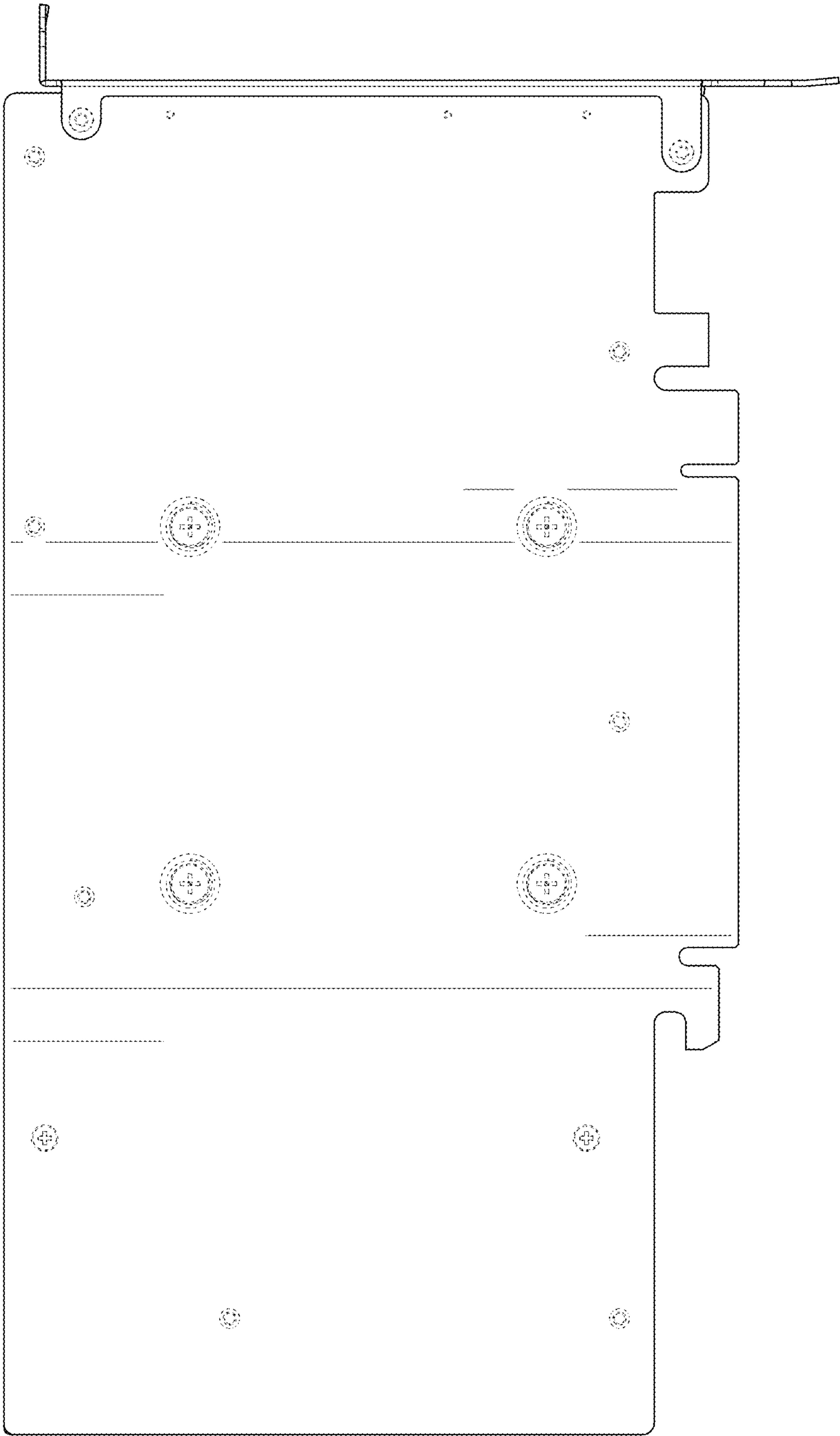


FIG. 4

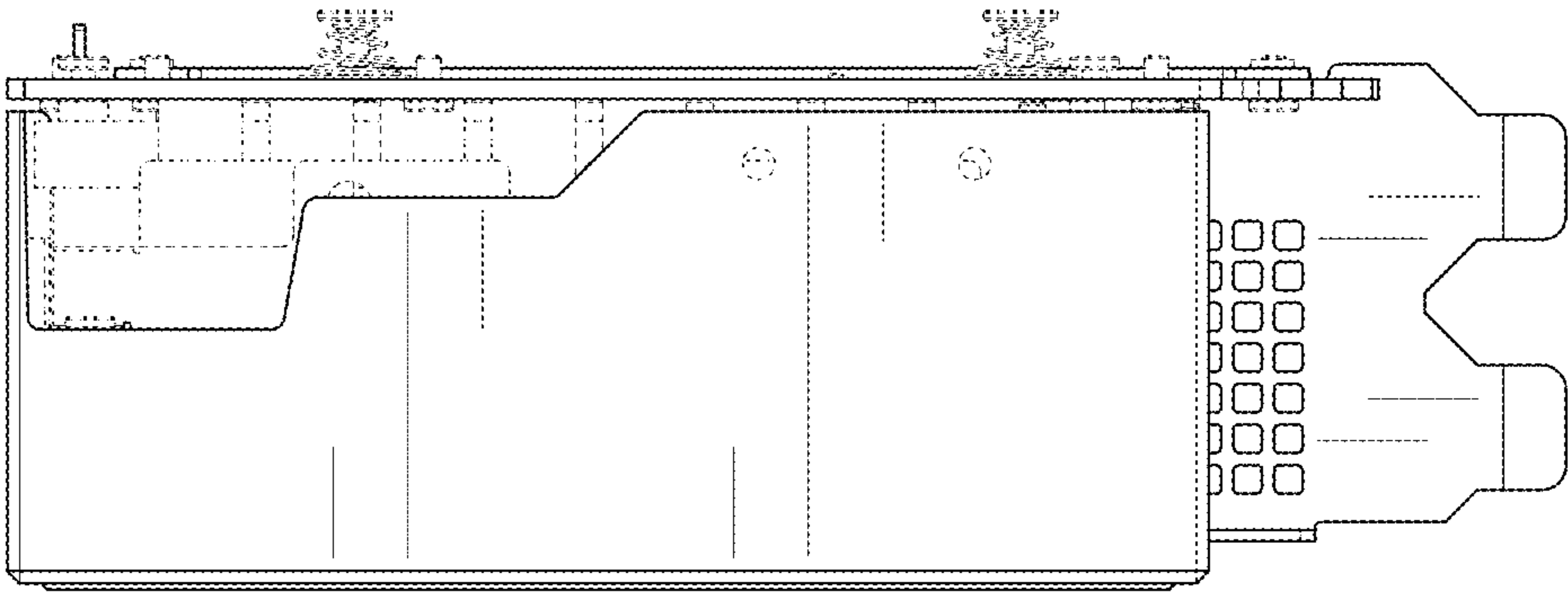


FIG. 5

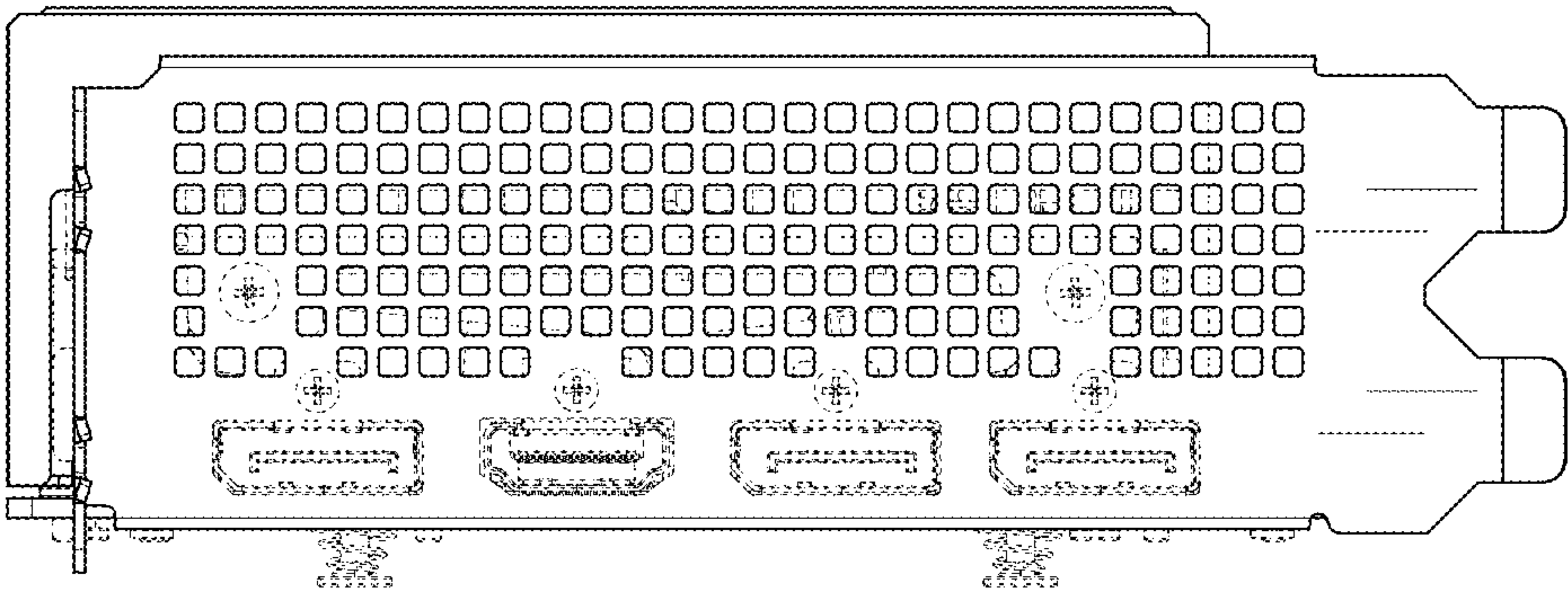


FIG. 6

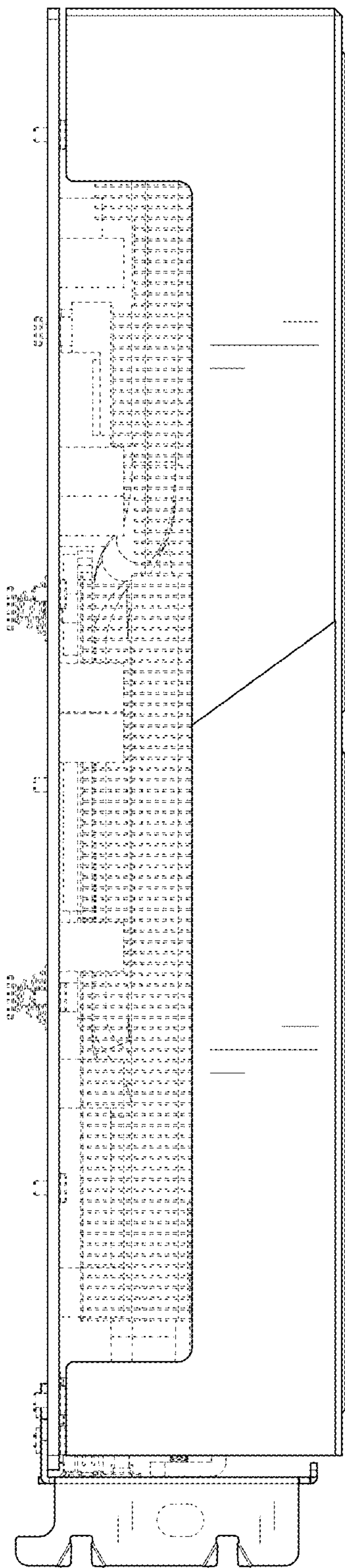


FIG. 7

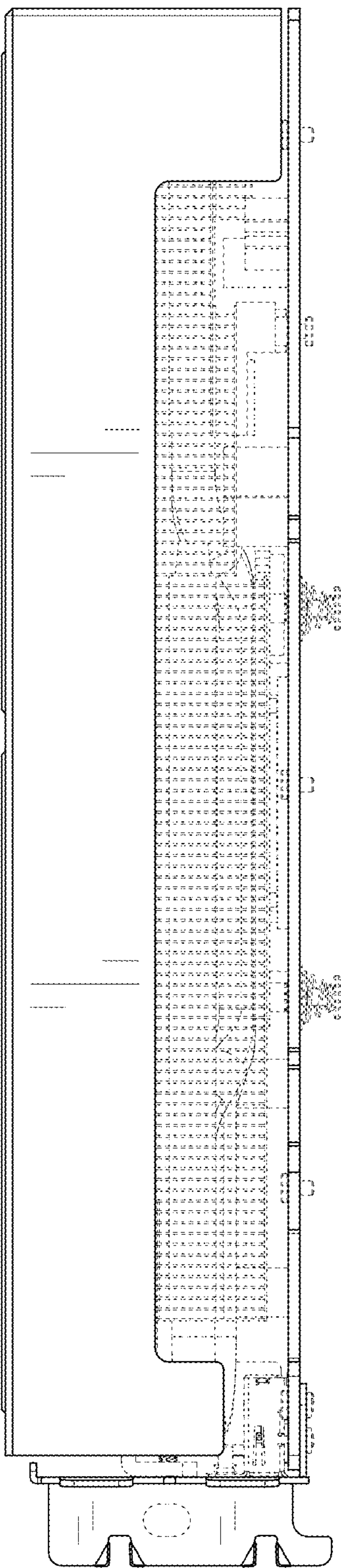


FIG. 8

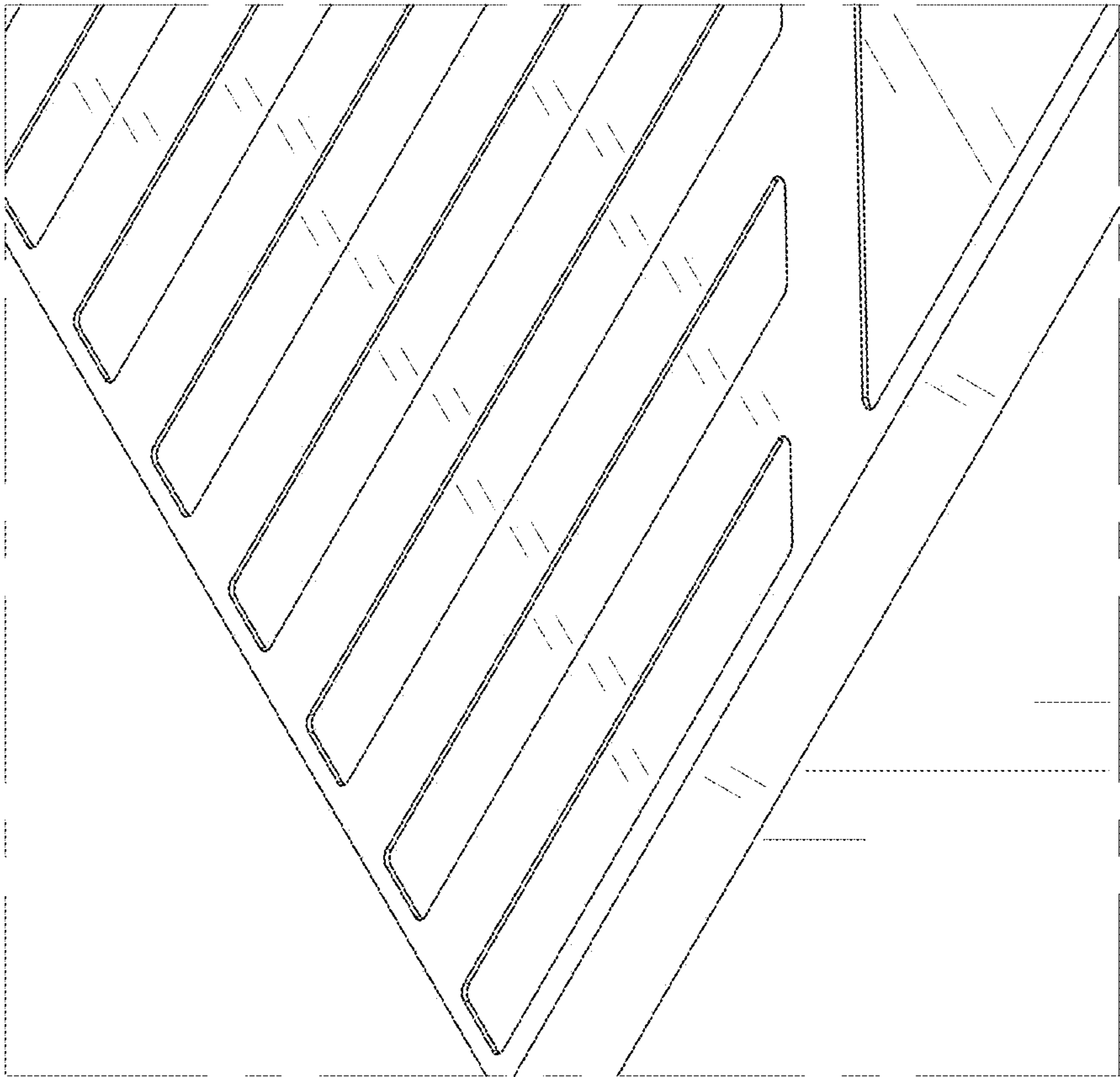


FIG. 9